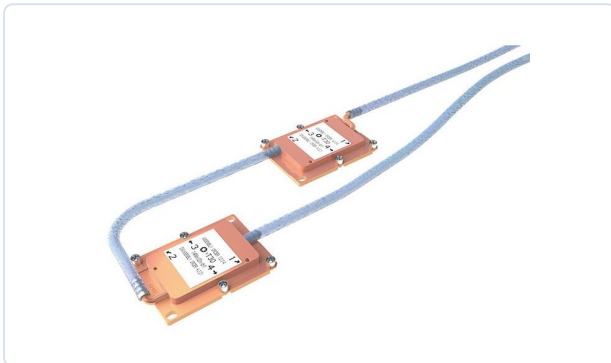


GPU / MULTI-GPU LIQUID COOLING MODULE

CDS-4U-2KW

High-capacity multi-GPU liquid cooling module (copper cold plates + manifold + radiator/CDU interface) for AI / HPC GPU servers; flow distribution and cold-plate interface engineered per GPU board.


REFERENCE OPERATING POINT

Cooling capacity up to ~2000 W

at validated coolant flow and inlet temperature; per-GPU thermal resistance and flow balance confirmed by CFD and test per board layout.

Engineering note: stated figures are design targets — confirmed per platform and system-level boundary conditions.

THERMAL PERFORMANCE

Cooling capacity (ref.)¹	up to ~2000 W
Per-GPU thermal resistance	CFD-validated per project
Flow distribution	Balanced across all GPU positions
Surface temp.	To GPU T_{case} limit

HYDRAULIC / FLUID

Coolant	DI water / inhibited water-glycol (per project)
Coolant flow rate	Per board & CDU budget
Pressure drop	CFD / test-validated
Max operating pressure	≤ 1.0 MPa typ.
Wetted materials	Copper cold plates, brazed; manifold

MECHANICAL

Cold plates	Copper, micro-channel; per GPU package
Manifold	Integrated; parallel flow
Mounting	Per GPU board / chassis
Radiator / interface	Customer radiator or CDU loop
Footprint	Per GPU board layout
Mass	Per configuration

RELIABILITY, TEST & COMPLIANCE

Leak test (100%)	Helium $\leq 1 \times 10^{-9}$ mbar-L/s or pressure test; criteria per project
Proof / burst pressure	Tested per project requirement
Thermal cycling	Per IEC 60068-2-14
Inspection	Ultrasonic C-scan per ASTM E2375 (bonded parts)
Compliance	RoHS; REACH & CE documentation on request

Send your platform / module, heat load, coolant, flow rate, inlet temperature, airflow & mechanical envelope — ToneCooling returns a CFD-supported design proposal and quotation.